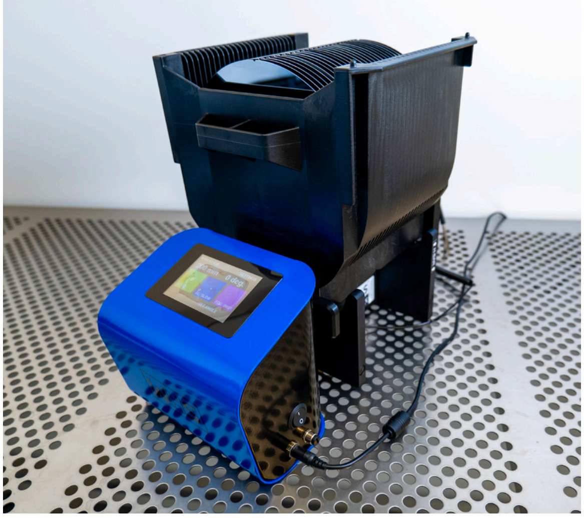
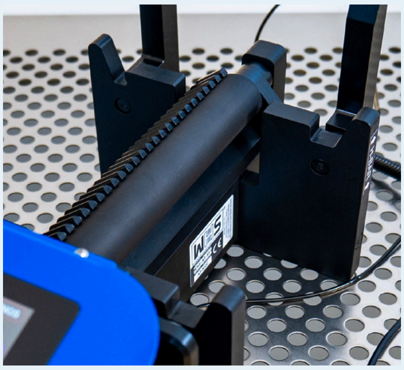
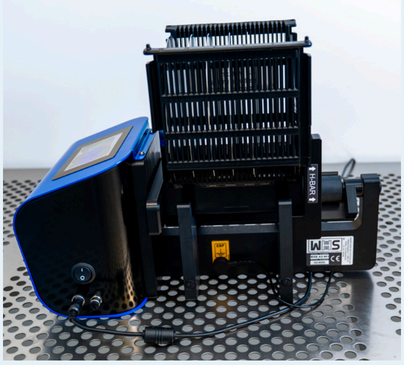
AUTOMATIC WAFER NOTCH ALIGNER

The WHS-A3 series is a cutting-edge automatic wafer notch aligner, designed for accurate ±1° bulk alignment of 150 mm (6”) or 200 mm (8”) notch wafers. This advanced system features a precision notch catch comb assembly, combined with an ESD-safe polyurethane roller, to ensure reliable and safe handling of sensitive semiconductor materials such as SiC, GaN, and GaAs. It is ideal for critical processes like lithography, deposition, and etching.

With a password-protected touchscreen interface, operators can access multiple alignment programs, including standard mode, thin/compound wafer alignment, and edge-inspection mode. The WHS-A3 offers exceptional flexibility for adapting to various wafer handling requirements, all while maintaining the highest precision.







Constructed with static dissipative materials, the WHS-A3 provides robust ESD protection by grounding both the wafer and cassette, safeguarding against electrostatic discharge during handling. This system is engineered to operate in ISO 3 (Class 1 FS209E) cleanroom environments, meeting the highest standards for contamination control.

The WHS-A3 also supports essential tasks like lot integrity checks and edge inspections, ensuring operators can identify and address wafer defects early in the process. Designed with easy maintenance in mind, it features a quick-disconnect roller assembly for fast and simple cleaning.

Manufactured in an ISO9001 and CE certified facility, the WHS-A3 meets rigorous international standards, making it the ideal solution for high-precision wafer alignment in demanding semiconductor production environments.

FEATURES AND ADVANTAGES

- Antistatic construction with grounded wafer and cassette paths
- Multiple alignment programs: standard, thin/compound wafer, and edge inspection
- ±1° notch alignment accuracy for 150 mm and 200 mm wafers
- ESD-safe polyurethane roller and precision notch catch comb assembly
- Ideal for alignment, lot integrity checks, and wafer edge inspection

AUTOMATIC WAFER NOTCH ALIGNER

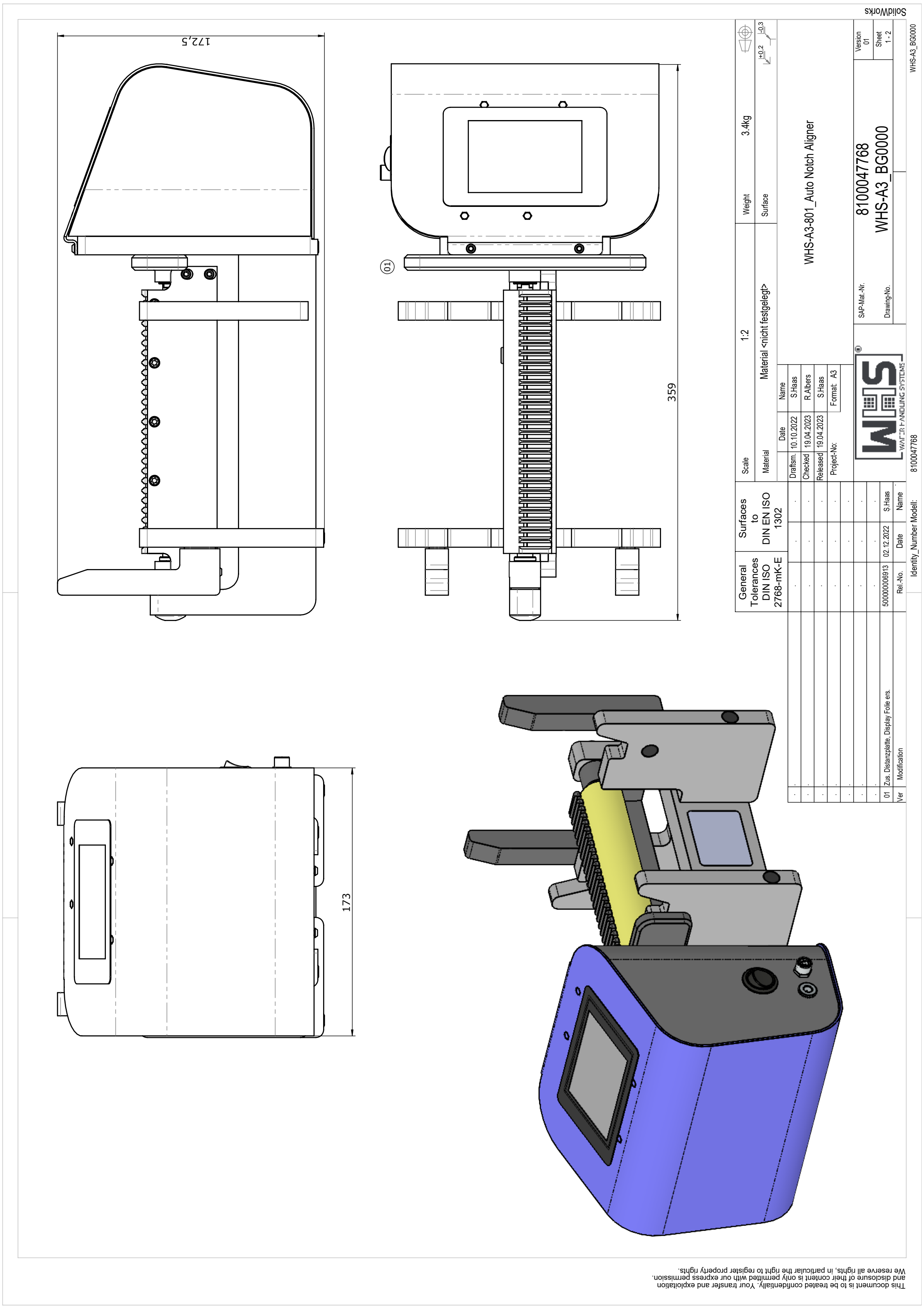
ITEM	SPECIFICATIONS
Wafer size	150 mm or 200 mm
Base material	Antistatic Polyoxymethylene
Roller material	Antistatic Polyurethane
Cleanliness	ISO 3 (Class 1 FS209E)
Replacement drive roller	WHS-SP-A3/A4-R8
Replacement notch roller	WHS-SP-A3/A4-NylonRod

*** NOTE: *Please specify cassette model number(s) when ordering* ***

ORDERING INFORMATION

WHS-A3- 801

CODE	MODEL	
	601	Aligner, automatic notch finder, 150 mm
	801	Aligner, automatic notch finder, 200 mm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173
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Surfaces to DIN EN ISO 1302
Scale 1:2
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Material Material <nicht festgelegt>
Surface
±0,2
-0,3
Date
Name
Draftsm. 10.10.2022 S.Haas
Checked 19.04.2023 R.Albers
Released 19.04.2023 S.Haas
Project-No:
Format: A3
WHS-A3-801_Auto Notch Aligner
SAP-Mat.-Nr. 8100047768
Drawing-No. WHS-A3_BG0000
Version 01
Sheet 1 - 2
01 Zus. Distanzplatte, Display Folie ers. 5000000006913 02.12.2022 S.Haas
Ver Modification Rel.-No. Date Name
Identity_Number Modell: 8100047768
WHS-A3_BG0000
WAFER HANDLING SYSTEMS
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